

## 08-25-2004



FORM PTO-1595 (Rev. 10/02) RECORI 102821086

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

Docket No.: 60188-835 20.04 PATENTS	ONLY			
To the Honorable Commissioner for Patents and Trademarks: Pl				
1. Name of Conveying Party(ies):	2. Name and address of receiving party(ies):			
Takumi MIKAWA, Yuji JUDAI and Toshie KUTSUNAI	Name: Matsushita Electric Industrial Co., Ltd.			
	Address: 1006, Oaza Kadoma			
Additional name(s) of conveying party(ies) attached? Yes No	Kadoma-shi, Osaka, Japan 571-8501			
3. Nature of Conveyance:				
☐ Security Agreement ☐ Change of Name				
Other				
Execution Date: July 8, 2004				
	Additional name(s) & address(es) attached?  Yes  No			
4. Application number(s) or patent number(s):				
If the document is being filed together with a new application, the	execution date of theapplication is:			
A. Patent Application No(s).	B. Patent No(s).			
10/823,797, filed April 14, 2004				
Additional numbers attac	ched? Yes No			
5. Name and address of party to whom correspondence	6. Total number of applications and patents involved:			
concerning document should be mailed:				
Name: MCDERMOTT WILL & EMERY LLP	7. Total fee (37 CFR 3.41) \$40.00			
Internal Address:	Enclosed			
	Authorized to be charged to deposit account			
Street Address: 600 13th Street, N.W.	8. Deposit account number:			
	500417			
City: Washington State: D. C. Zip: 20005-3096				
DO NOT HIS THIS COLOR				
DO NOT USE THIS SPACE				
9. Statement and signature.	ture and compat and any attached any in			
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy				
of the original document.				
Michael E. Fogarty, Registration No. 36,139	August 20, 2004			
Name and Registration No. of Person Signing	Signature Date			
<i>f</i>	otal number of pages including cover sheet: 3			
MB No. 0651-0027 (exp. 6/30/2005)				

08/24/2004 MGETACHE 00000209 500417 10823797 01 FC:8021 40.00 DA

> PATENT REEL: 015702 FRAME: 0625

Attorney Docket No
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## ASSIGNMENT

	W)	HEREAS,	Takumi MIKAWA, Yuji JUDAI and Toshie KUTSUNAI		
(herein	after	designated	as the undersigned) has (have) invented certain new and useful improvements		
in	in SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME				
			for which the undersigned has (have):		
	(a)		plication for Letters Patent of the United States of America on , 2004 having Serial No. 10/823,797; or		
	(b)	executed indicated	n application for Letters Patent of the United States of America on the date(s) elow; and		
	W	HEREAS,	Matsushita Electric Industrial Co., Ltd. of		
1006, 0	Daza	Kadoma,	Kadoma-shi, Osaka 571-8501, Japan		
its heir	s, su	ccessors, le	gal representatives and assigns (hereinafter designated as the Assignee) is		
desirou	s of	acquiring t	e entire right, title and interest in and to said invention and in and to any Letters		
Patent(	s) th	at may be	ranted therefor in the United States of America;		

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer unto the Assignee the full and exclusive right to the said invention in the United States of America and its territories and for all foreign countries, dependencies and possessions and the entire right, title and interest in and to the application and any and all Letters Patent(s) which may be granted therefor in the United States of America and its territories, dependencies and possessions, and in and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or any continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims under or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

PATENT REEL: 015702 FRAME: 0626 The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to the Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States of America resulting from said application or any division or divisions or continuing or reissue applications thereof to the Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

This Assignment has been executed by the undersigned on the date(s) indicated.

Date:	July 8, 2004	Takumi Mihawa
	***	Takumi MIKAWA
Date:	July 8, 2004	Yuji Judai Yuji JUDAI
		Yuji JUDAI
Date:	July 8, 2004 ,	Toshie Kutsinai
		Toshie KUTSUNAI
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**RECORDED: 08/20/2004** 

PATENT REEL: 015702 FRAME: 0627